

#### **GENERAL PURPOSE AMPLIFIER**

**RoHS Compliant & Pb-Free Product** Package Style: S0T89

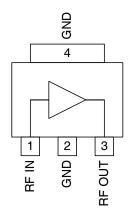


#### **Features**

- DC to >6000MHz Operation
- Internally Matched Input and Output
- 13.2dB Small Signal Gain
- +28dBm Output IP3
- +16.0dBm Output P1dB

#### **Applications**

- Basestation Applications
- Broadband, Low-Noise Gain **Blocks**
- IF or RF Buffer Amplifiers
- Driver Stage for Power Amplifiers
- Final PA for Low-Power Applications
- High Reliability Applications



**Functional Block Diagram** 

#### **Product Description**

The RF3375 is a general purpose, low-cost RF amplifier IC. The device is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (HBT) process, and has been designed for use as an easily-cascadable  $50\Omega$  gain block. Applications include IF and RF amplification in wireless voice and data communication products operating in frequency bands up to 6000 MHz. The device is self-contained with  $50\Omega$  input and output impedances and requires only two external DCbiasing elements to operate as specified.

#### **Ordering Information**

RF3375 General Purpose Amplifier RF337XPCBA-41X Fully Assembled Evaluation Board

#### **Optimum Technology Matching® Applied**

☐ SiGe BiCMOS	☐ GaAs pHEMT	☐ GaN HEMT
☐ Si BiCMOS	☐ Si CMOS	
☐ SiGe HBT	☐ Si BJT	
	☐ Si BiCMOS	☐ Si BiCMOS ☐ Si CMOS



#### **Absolute Maximum Ratings**

Parameter	Rating	Unit
Input RF Power	+13	dBm
Operating Ambient Temperature	-40 to +85	°C
Storage Temperature	-60 to +150	°C
Icc	80	mA



#### Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

RoHS status based on EU Directive 2002/95/EC (at time of this document revision).

The information in this publication is believed to be accurate and reliable. However, no responsibility is assumed by RF Micro Devices, Inc. ("RFMD") for its use, nor for any infringement of patents, or other rights of third parties, resulting from its use. No license is granted by implication or otherwise under any patent or patent rights of RFMD. RFMD reserves the right to change component circuitry, recommended application circuitry and specifications at any time without prior notice.

Parameter	Specification		Unit	Condition		
Parameter	Min.	Тур.	Max.	Unit	Condition	
Overall	_				T=25 °C, I <sub>CC</sub> =65 mA (See Note 1.)	
Frequency Range		DC to >6000		MHz		
3dB Bandwidth		6		GHz		
Gain	12.5	13.5		dB	Freq=500MHz	
	12.5	13.5		dB	Freq=1000MHz	
	12.2	13.2		dB	Freq=2000MHz	
	12.2	13.2		dB	Freq=3000MHz	
	12.0	13.0			Freq=4000MHz	
	10.0	12.4			Freq=6000MHz	
Noise Figure		4.6		dB	Freq=2000MHz	
Input VSWR		<1.9:1			In a $50\Omega$ system, DC to $6000\text{MHz}$	
Output VSWR		<2.0:1			In a $50\Omega$ system, DC to $500  \text{MHz}$	
		<1.7:1			In a 50Ω system, 500MHz to 6000MHz	
Output IP <sub>3</sub>	+31.0	+33.9		dBm	Freq=1000MHz	
	+28.0	+30.0		dBm	Freq=2000MHz	
Output P <sub>1dB</sub>	+17.0	+18.5		dBm	Freq=1000MHz	
	+14.5	+16.0		dBm	Freq=2000MHz	
Reverse Isolation		-18.0		dB	Freq=2000MHz	
Thermal					I <sub>CC</sub> =65 mA, P <sub>DISS</sub> =313 mW. (See Note 3.)	
Theta <sub>JC</sub>		175		°C/W	V <sub>PIN</sub> =4.81V	
Maximum Measured Junction Temperature at DC Bias Conditions		139		°C	T <sub>CASE</sub> =+85°C	
Mean Time to Failures		1500		years	T <sub>CASE</sub> =+85 °C	
Power Supply					With $22\Omega$ bias resistor, T=+25°C	
Device Operating Voltage		5.18	5.36	V	At pin 8 with I <sub>CC</sub> =65mA	
		6.6	7.0	V	At Evaluation Board Connector I <sub>CC</sub> =65 mA	
Operating Current		65	80	mA	See Note 2.	

Note 1: All specification and characterization data has been gathered on standard FR-4 evaluation boards. These evaluation boards are not optimized for frequencies above 2.5 GHz. Performance above 2.5 GHz may improve if a high performance PCB is used.

Note 2: The RF3375 must be operated at or below 80 mA in order to achieve the thermal performance listed above. While the RF3375 may be operated at higher bias currents, 65 mA is the recommended bias to ensure the highest possible reliability and electrical performance.

Note 3: Because of process variations from part to part, the current resulting from a fixed bias voltage will vary. As a result, caution should be used in designing fixed voltage bias circuits to ensure the worst case bias current does not exceed 80 mA over all intended operating conditions.

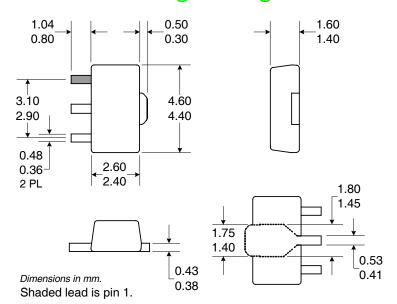






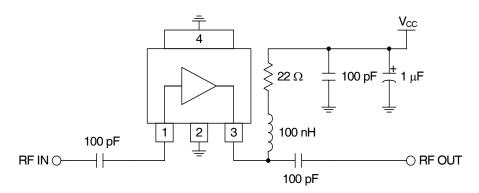
Pin	Function	Description	Interface Schematic
1	RF IN	RF input pin. This pin is NOT internally DC blocked. A DC blocking capacitor, suitable for the frequency of operation, should be used in most applications. DC coupling of the input is not allowed, because this will override the internal feedback loop and cause temperature instability.	
2	GND	Ground connection.	
3	RF OUT	RF output and bias pin. Biasing is accomplished with an external series resistor and choke inductor to $V_{CC}$ . The resistor is selected to set the DC current into this pin to a desired level. The resistor value is determined by the following equation: $R = \frac{(V_{SUPPLY} - V_{DEVICE})}{I_{CC}}$ Care should also be taken in the resistor selection to <b>ensure that the current into the part never exceeds 80 mA over the planned operating temperature.</b> This means that a resistor between the supply and this pin is always required, even if a supply near 5.0V is available, to provide DC feedback to prevent thermal runaway. Because DC is present on this pin, a DC blocking capacitor, suitable for the frequency of operation, should be used in most applications. The supply side of the bias network should also be well bypassed.	RF INO
4	GND	Ground connection.	

## **Package Drawing**



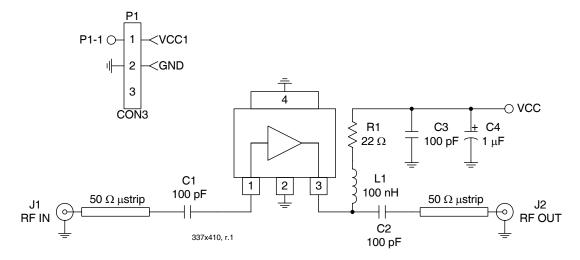


## **Application Schematic**



## **Evaluation Board Schematic**

(Download Bill of Materials from www.rfmd.com.)





# Evaluation Board Layout Board Size 1.195" x 1.000"

**Board Thickness 0.033", Board Material FR-4** 

